

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10598124			
<b>Filing Date:</b>	18-Aug-2006			
<b>Title of Invention:</b>	Solder composition and method of bump formation therewith			
<b>First Named Inventor/Applicant Name:</b>	Isao Sakamoto			
<b>Filer:</b>	Stephen M. Roylance/Timothy BOONE			
<b>Attorney Docket Number:</b>	P30245			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 1 month with \$0 paid	1251	1	130	130

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				940